

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|------------------|---|-----------------|-----------------|-------------------------|-------------------|
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.19502 | 100.0 | 4.08212 |
| | | | Subtotal | 0.19502 | 100 | 4.08212 |
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.19588 | 100.0 | 4.1 |
| | | | Subtotal | 0.19588 | 100 | 4.1 |
| Solder Wire | Tin alloy | Tin (Sn) | 7440-31-5 | 0.01795 | 10.0 | 0.37571 |
| | Silver alloy | Silver (Ag) | 7440-22-4 | 0.00359 | 2.0 | 0.07514 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.15795 | 88.0 | 3.3062 |
| | | | Subtotal | 0.17949 | 100 | 3.75705 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.01219 | 100.0 | 0.25513 |
| | | | Subtotal | 0.01219 | 100 | 0.25513 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.00702 | 0.03 | 0.14694 |
| | Pure metal layer | Zinc (Zn) | 7440-66-6 | 0.00468 | 0.02 | 0.09796 |
| | Pure metal layer | Tin (Sn) | 7440-31-5 | 0.00702 | 0.03 | 0.14694 |
| | Pure metal layer | Iron (Fe) | 7439-89-6 | 0.02574 | 0.11 | 0.53877 |
| | Pure metal layer | Copper (Cu) | 7440-50-8 | 23.35519 | 99.81 | 488.8594 |
| | | | Subtotal | 23.39965 | 100 | 489.79001 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 0.24685 | 100.0 | 5.167 |
| | | | Subtotal | 0.24685 | 100 | 5.167 |
| Mould Compound | Polymer | Tetrabromobisphenol A/Epichlorohydrin polymer | 40039-93-8 | 2.27313 | 3.0 | 47.58 |
| | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 4.54626 | 6.0 | 95.16 |
| | Polymer | Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic) | 29690-82-2 | 7.57709 | 10.0 | 158.6 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.37885 | 0.5 | 7.93 |
| | Filler | Misc. Silica compounds (generic) | 14808-60-7 | 59.10132 | 78.0 | 1237.08 |
| | Flame retardant | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4 | 1309-64-4 | 1.89427 | 2.5 | 39.65 |
| | | | Subtotal | 75.77092 | 100 | 1586 |
| | | | Total | 100 | 100 | 2093.15131 |

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.